TIDA-00277: Automotive Cluster Chime Reference Design – Design Considerations

This document discusses design details that should be considered when driving an automotive cluster chime.

- Avoid clipping of the sine wave. For this set up, the waveform clips at 3.12Vpp and does not clip at 2.16Vpp. One of the reasons for clipping is the voltage swing of the amplifier.
- dB meter should be placed at a distance of 4-5x the size of the diameter of the speaker.
- MSP430 can be other option for a function generator. The code example provided utilizes Timer A to generate a varying duty cycle single ended PWM.
 The code as is outputs a noisy sine wave. To optimize the code, a higher order filter is needed and the sine wave array needs to be modified.
- If filtering is used, the filters on both inputs to the amplifier must be identical. If a single ended PWM is implemented, ground one of the filters.

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